

IN THE CLAIMS:

Please cancel claims ~~13-20~~.

Please amend the following claims:

1. (Amended) A laminate support used in the process of wire bonding a circuit device comprising:

a substrate having a first surface; and

a wire having a diameter positioned on said first surface of said substrate, said substrate including a closed woven mesh having strands whose separation distance is equal to or less than said diameter of said wire on said first surface of said substrate.

4. (Amended) The laminate support used in the process of wire bonding a circuit device in accordance with claim 1, wherein said woven mesh comprises fiberglass.

5. (Amended) The laminate support used in the process of wire bonding a circuit device in accordance with claim 1, wherein said woven mesh is between approximately 2.5 and 4.0 mils thick.

7. (Amended) A laminate support used in the process of wire bonding a circuit device comprising:

a substrate having a first surface; and

a wire having a thickness positioned on said first surface of said substrate, said substrate including a closed woven mesh having warp and weave strands, whose separation distance is equal to or less than the thickness of said wire on said first surface of said